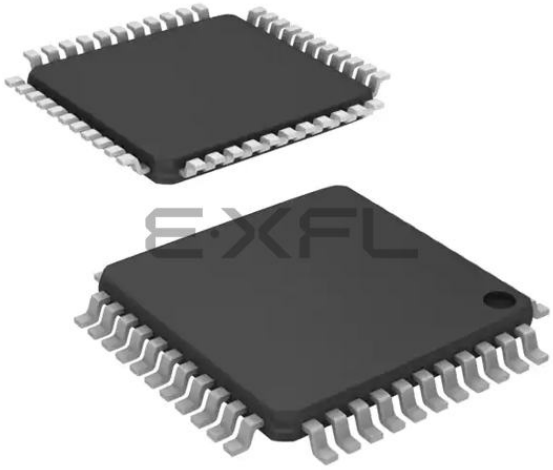
Microchip Technology - PIC24EP32MC204T-E/PT Datasheet



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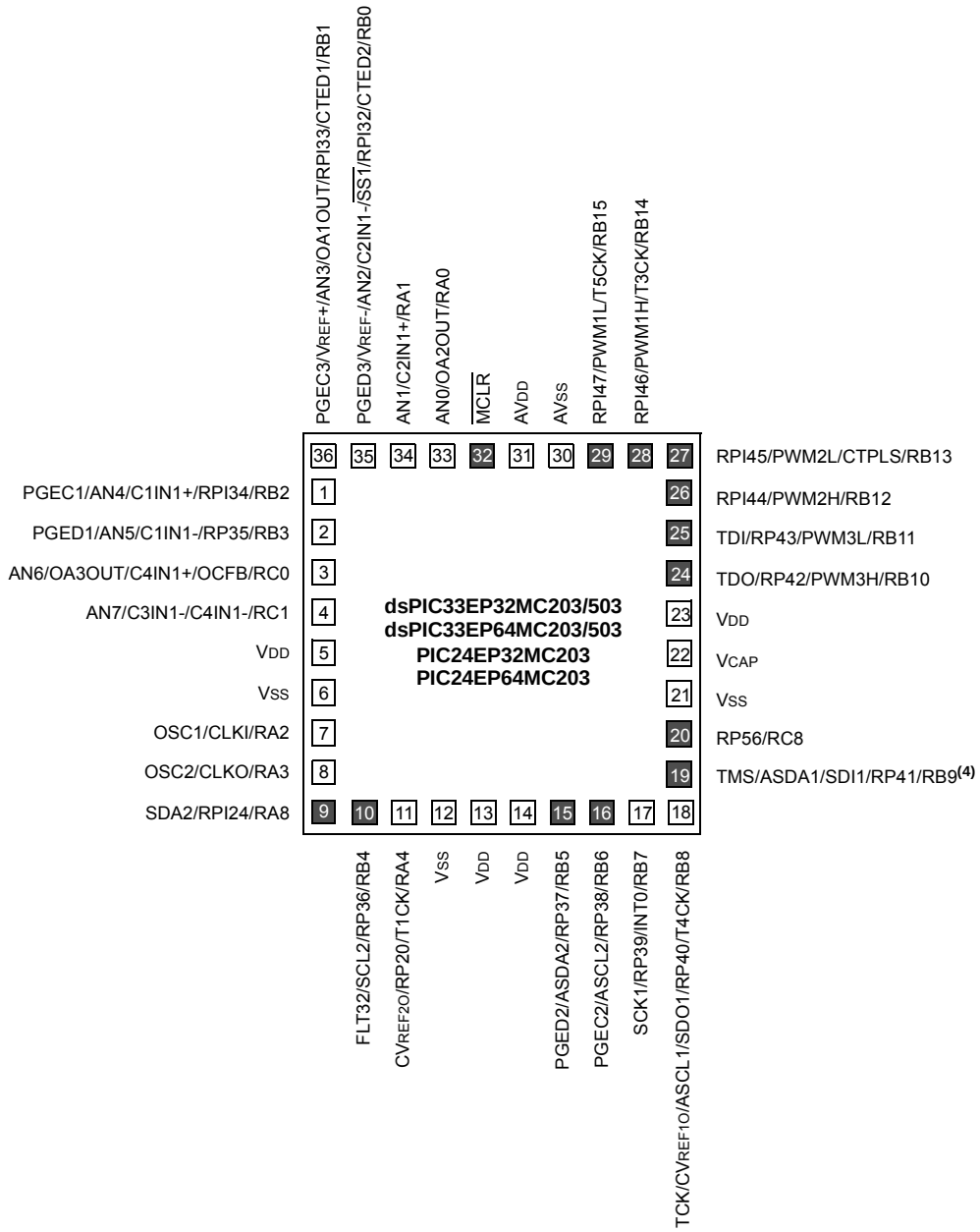
Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	PIC
Core Size	16-Bit
Speed	60 MIPs
Connectivity	I²C, IrDA, LINbus, QEI, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, Motor Control PWM, POR, PWM, WDT
Number of I/O	35
Program Memory Size	32KB (10.7K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	2K x 16
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 9x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	44-TQFP
Supplier Device Package	44-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic24ep32mc204t-e-pt

Pin Diagrams (Continued)

36-Pin VTLA(1,2,3)

■ = Pins are up to 5V tolerant



Note 1: The RPn/RPIn pins can be used by any remappable peripheral with some limitation. See **Section 11.4 "Peripheral Pin Select (PPS)"** for available peripherals and for information on limitations.

2: Every I/O port pin (RAx-RGx) can be used as a Change Notification pin (CNAx-CNGx). See **Section 11.0 "I/O Ports"** for more information.

3: The metal pad at the bottom of the device is not connected to any pins and is recommended to be connected to VSS externally.

4: There is an internal pull-up resistor connected to the TMS pin when the JTAG interface is active. See the JTAGEN bit field in Table 27-2.

REGISTER 3-2: CORCON: CORE CONTROL REGISTER (CONTINUED)

bit 2 **SFA:** Stack Frame Active Status bit
- 1 = Stack frame is active; W14 and W15 address 0x0000 to 0xFFFF, regardless of DSRPAG and DSWPAG values
- 0 = Stack frame is not active; W14 and W15 address of EDS or Base Data Space

bit 1 **RND:** Rounding Mode Select bit(1)
- 1 = Biased (conventional) rounding is enabled
- 0 = Unbiased (convergent) rounding is enabled

bit 0 **IF:** Integer or Fractional Multiplier Mode Select bit(1)
- 1 = Integer mode is enabled for DSP multiply
- 0 = Fractional mode is enabled for DSP multiply

Note 1: This bit is available on dsPIC33EPXXXMC20X/50X and dsPIC33EPXXXGP50X devices only.

2: This bit is always read as '0'.

3: The IPL3 bit is concatenated with the IPL<2:0> bits (SR<7:5>) to form the CPU Interrupt Priority Level.

TABLE 4-11: PTG REGISTER MAP

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
PTGCST	0AC0	PTGEN	—	PTGSIDL	PTGTOGL	—	PTGSWT	PTGSSEN	PTGIVIS	PTGSTRT	PTGWTO	—	—	—	—	PTGITM<1:0>		0000
PTGCON	0AC2	PTGCLK<2:0>			PTGDIV<4:0>					PTGPWD<3:0>				—	PTGWDT<2:0>			0000
PTGBTE	0AC4	ADCTS<4:1>				IC4TSS	IC3TSS	IC2TSS	IC1TSS	OC4CS	OC3CS	OC2CS	OC1CS	OC4TSS	OC3TSS	OC2TSS	OC1TSS	0000
PTGHOLD	0AC6	PTGHOLD<15:0>																0000
PTGT0LIM	0AC8	PTGT0LIM<15:0>																0000
PTGT1LIM	0ACA	PTGT1LIM<15:0>																0000
PTGSDLIM	0ACC	PTGSDLIM<15:0>																0000
PTGC0LIM	0ACE	PTGC0LIM<15:0>																0000
PTGC1LIM	0AD0	PTGC1LIM<15:0>																0000
PTGADJ	0AD2	PTGADJ<15:0>																0000
PTGL0	0AD4	PTGL0<15:0>																0000
PTGQPTR	0AD6	—	—	—	—	—	—	—	—	—	—	—	PTGQPTR<4:0>					0000
PTGQUE0	0AD8	STEP1<7:0>								STEP0<7:0>								0000
PTGQUE1	0ADA	STEP3<7:0>								STEP2<7:0>								0000
PTGQUE2	0ADC	STEP5<7:0>								STEP4<7:0>								0000
PTGQUE3	0ADE	STEP7<7:0>								STEP6<7:0>								0000
PTGQUE4	0AE0	STEP9<7:0>								STEP8<7:0>								0000
PTGQUE5	0AE2	STEP11<7:0>								STEP10<7:0>								0000
PTGQUE6	0AE4	STEP13<7:0>								STEP12<7:0>								0000
PTGQUE7	0AE6	STEP15<7:0>								STEP14<7:0>								0000

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-27: PERIPHERAL PIN SELECT OUTPUT REGISTER MAP FOR dsPIC33EPXXXGP/MC204/504 AND PIC24EPXXXGP/MC204 DEVICES ONLY

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
RPOR0	0680	—	—	RP35R<5:0>						—	—	RP20R<5:0>						0000
RPOR1	0682	—	—	RP37R<5:0>						—	—	RP36R<5:0>						0000
RPOR2	0684	—	—	RP39R<5:0>						—	—	RP38R<5:0>						0000
RPOR3	0686	—	—	RP41R<5:0>						—	—	RP40R<5:0>						0000
RPOR4	0688	—	—	RP43R<5:0>						—	—	RP42R<5:0>						0000
RPOR5	068A	—	—	RP55R<5:0>						—	—	RP54R<5:0>						0000
RPOR6	068C	—	—	RP57R<5:0>						—	—	RP56R<5:0>						0000

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-28: PERIPHERAL PIN SELECT OUTPUT REGISTER MAP FOR dsPIC33EPXXXGP/MC206/506 AND PIC24EPXXXGP/MC206 DEVICES ONLY

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
RPOR0	0680	—	—	RP35R<5:0>						—	—	RP20R<5:0>						0000
RPOR1	0682	—	—	RP37R<5:0>						—	—	RP36R<5:0>						0000
RPOR2	0684	—	—	RP39R<5:0>						—	—	RP38R<5:0>						0000
RPOR3	0686	—	—	RP41R<5:0>						—	—	RP40R<5:0>						0000
RPOR4	0688	—	—	RP43R<5:0>						—	—	RP42R<5:0>						0000
RPOR5	068A	—	—	RP55R<5:0>						—	—	RP54R<5:0>						0000
RPOR6	068C	—	—	RP57R<5:0>						—	—	RP56R<5:0>						0000
RPOR7	068E	—	—	RP97R<5:0>						—	—	—	—	—	—	—	—	0000
RPOR8	0690	—	—	RP118R<5:0>						—	—	—	—	—	—	—	—	0000
RPOR9	0692	—	—	—	—	—	—	—	—	—	—	RP120R<5:0>						0000

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

4.4.2 EXTENDED X DATA SPACE

The lower portion of the base address space range, between 0x0000 and 0x7FFF, is always accessible regardless of the contents of the Data Space Page registers. It is indirectly addressable through the register indirect instructions. It can be regarded as being located in the default EDS Page 0 (i.e., EDS address range of 0x000000 to 0x007FFF with the base address bit, EA<15> = 0, for this address range). However, Page 0 cannot be accessed through the upper 32 Kbytes, 0x8000 to 0xFFFF, of base Data Space, in combination with DSRPAG = 0x000 or DSWPAG = 0x000. Consequently, DSRPAG and DSWPAG are initialized to 0x001 at Reset.

Note 1: DSxPAG should not be used to access Page 0. An EDS access with DSxPAG set to 0x000 will generate an address error trap.

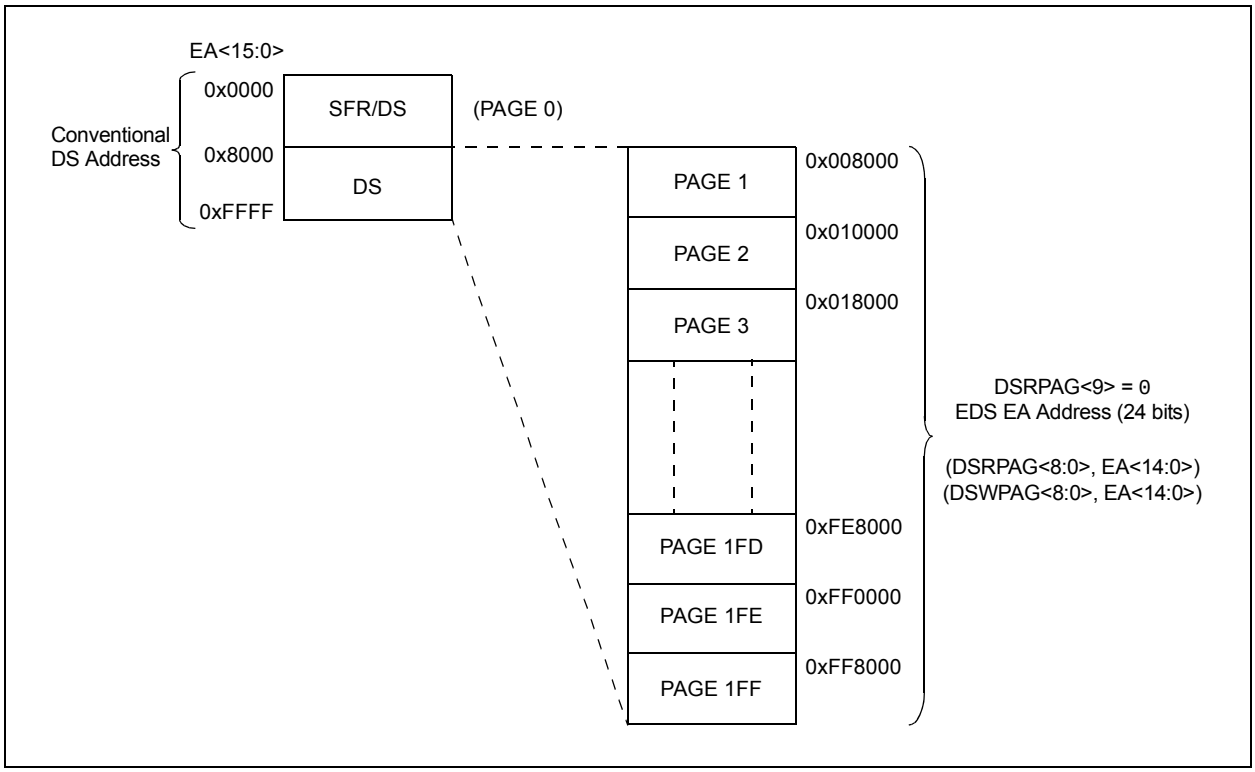
2: Clearing the DSxPAG in software has no effect.

The remaining pages, including both EDS and PSV pages, are only accessible using the DSRPAG or DSWPAG registers in combination with the upper 32 Kbytes, 0x8000 to 0xFFFF, of the base address, where base address bit, EA<15> = 1.

For example, when DSRPAG = 0x001 or DSWPAG = 0x001, accesses to the upper 32 Kbytes, 0x8000 to 0xFFFF, of the Data Space will map to the EDS address range of 0x008000 to 0x00FFFF. When DSRPAG = 0x002 or DSWPAG = 0x002, accesses to the upper 32 Kbytes of the Data Space will map to the EDS address range of 0x010000 to 0x017FFF and so on, as shown in the EDS memory map in Figure 4-17.

For more information on the PSV page access using Data Space Page registers, refer to the **"Program Space Visibility from Data Space"** section in **"Program Memory"** (DS70613) of the *"dsPIC33/PIC24 Family Reference Manual"*.

FIGURE 4-17: EDS MEMORY MAP



REGISTER 6-1: RCON: RESET CONTROL REGISTER(1)

R/W-0	R/W-0	U-0	U-0	R/W-0	U-0	R/W-0	R/W-0
TRAPR	IOPUWR	—	—	VREGSF	—	CM	VREGS
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-1	R/W-1
EXTR	SWR	SWDTEN(2)	WDTO	SLEEP	IDLE	BOR	POR
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **TRAPR:** Trap Reset Flag bit
1 = A Trap Conflict Reset has occurred
0 = A Trap Conflict Reset has not occurred

bit 14 **IOPUWR:** Illegal Opcode or Uninitialized W Access Reset Flag bit
1 = An illegal opcode detection, an illegal address mode or Uninitialized W register used as an Address Pointer caused a Reset
0 = An illegal opcode or Uninitialized W register Reset has not occurred

bit 13-12 **Unimplemented:** Read as '0'

bit 11 **VREGSF:** Flash Voltage Regulator Standby During Sleep bit
1 = Flash voltage regulator is active during Sleep
0 = Flash voltage regulator goes into Standby mode during Sleep

bit 10 **Unimplemented:** Read as '0'

bit 9 **CM:** Configuration Mismatch Flag bit
1 = A Configuration Mismatch Reset has occurred.
0 = A Configuration Mismatch Reset has not occurred

bit 8 **VREGS:** Voltage Regulator Standby During Sleep bit
1 = Voltage regulator is active during Sleep
0 = Voltage regulator goes into Standby mode during Sleep

bit 7 **EXTR:** External Reset ($\overline{\text{MCLR}}$) Pin bit
1 = A Master Clear (pin) Reset has occurred
0 = A Master Clear (pin) Reset has not occurred

bit 6 **SWR:** Software RESET (Instruction) Flag bit
1 = A RESET instruction has been executed
0 = A RESET instruction has not been executed

bit 5 **SWDTEN:** Software Enable/Disable of WDT bit(2)
1 = WDT is enabled
0 = WDT is disabled

bit 4 **WDTO:** Watchdog Timer Time-out Flag bit
1 = WDT time-out has occurred
0 = WDT time-out has not occurred

Note 1: All of the Reset status bits can be set or cleared in software. Setting one of these bits in software does not cause a device Reset.

2: If the FWDTEN Configuration bit is '1' (unprogrammed), the WDT is always enabled, regardless of the SWDTEN bit setting.

9.0 OSCILLATOR CONFIGURATION

Note 1: This data sheet summarizes the features of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"Oscillator"** (DS70580) in the "*dsPIC33/PIC24 Family Reference Manual*", which is available from the Microchip web site (www.microchip.com).

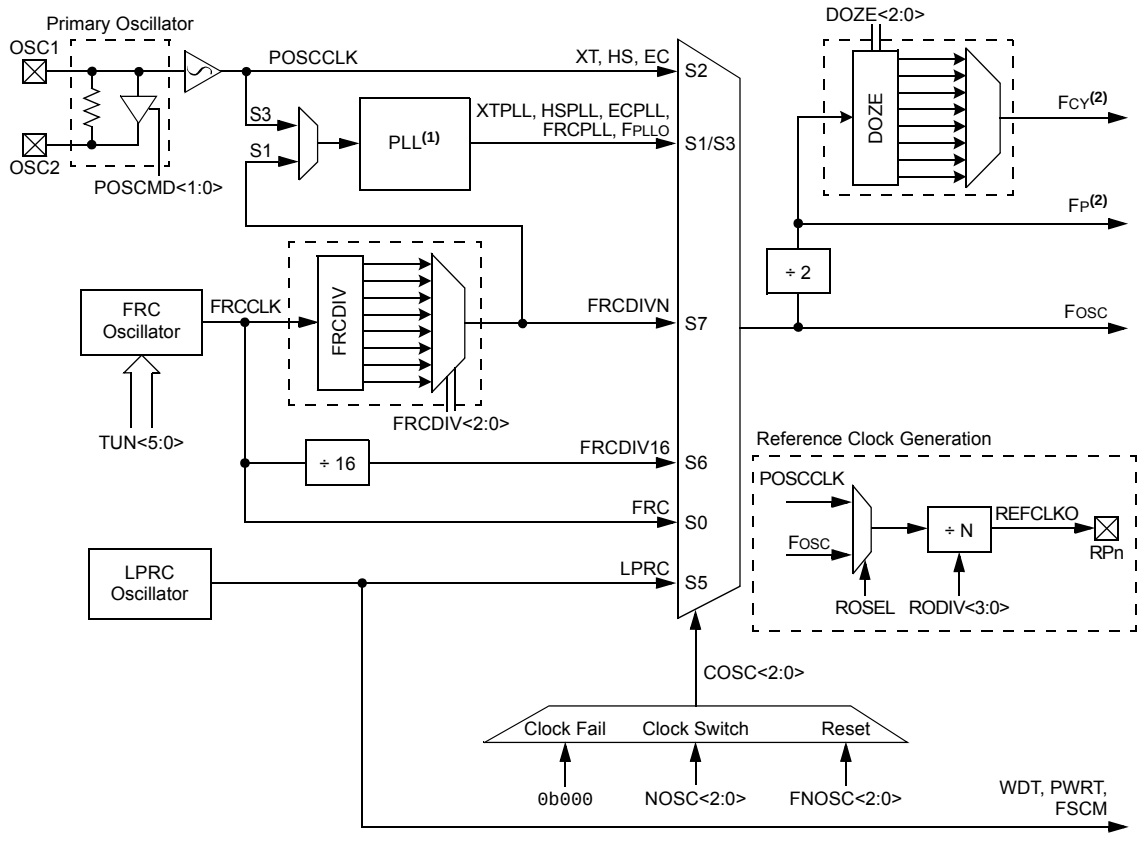
2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X oscillator system provides:

- On-chip Phase-Locked Loop (PLL) to boost internal operating frequency on select internal and external oscillator sources
- On-the-fly clock switching between various clock sources
- Doze mode for system power savings
- Fail-Safe Clock Monitor (FSCM) that detects clock failure and permits safe application recovery or shutdown
- Configuration bits for clock source selection

A simplified diagram of the oscillator system is shown in Figure 9-1.

FIGURE 9-1: OSCILLATOR SYSTEM DIAGRAM



Note 1: See Figure 9-2 for PLL details.

2: The term, FP, refers to the clock source for all peripherals, while FCY refers to the clock source for the CPU. Throughout this document, FCY and FP are used interchangeably, except in the case of Doze mode. FP and FCY will be different when Doze mode is used with a doze ratio of 1:2 or lower.

9.1 CPU Clocking System

The dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X family of devices provides six system clock options:

- Fast RC (FRC) Oscillator
- FRC Oscillator with Phase Locked Loop (PLL)
- FRC Oscillator with Postscaler
- Primary (XT, HS or EC) Oscillator
- Primary Oscillator with PLL
- Low-Power RC (LPRC) Oscillator

Instruction execution speed or device operating frequency, FCY, is given by Equation 9-1.

EQUATION 9-1: DEVICE OPERATING FREQUENCY

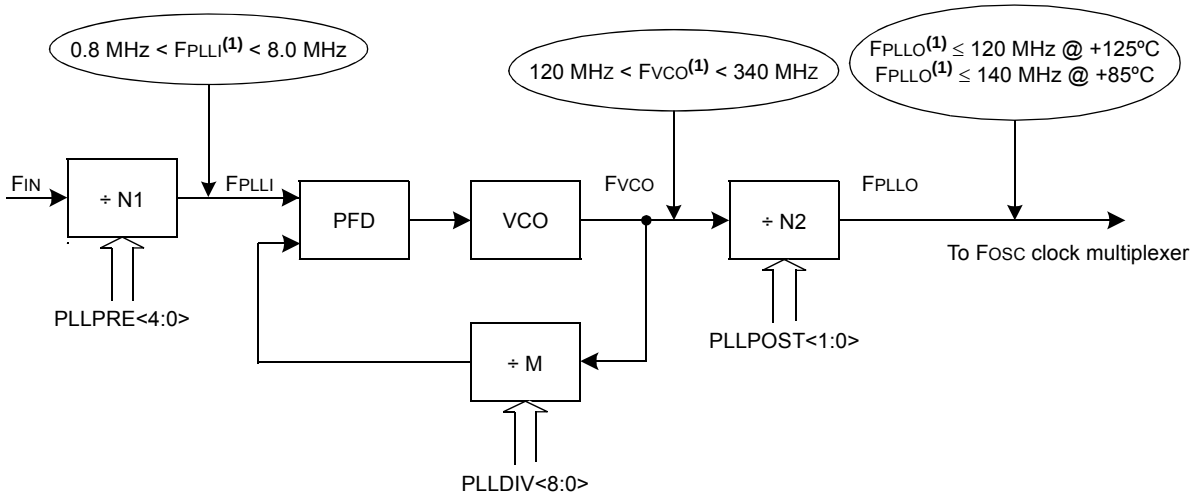
$$FCY = Fosc/2$$

Figure 9-2 is a block diagram of the PLL module.

Equation 9-2 provides the relationship between input frequency (FIN) and output frequency (FPLLO). In clock modes S1 and S3, when the PLL output is selected, FOSC = FPLLO.

Equation 9-3 provides the relationship between input frequency (FIN) and VCO frequency (FVCO).

FIGURE 9-2: PLL BLOCK DIAGRAM



Note 1: This frequency range must be met at all times.

EQUATION 9-2: FPLLO CALCULATION

$$FPLLO = FIN \times \left(\frac{M}{N1 \times N2}\right) = FIN \times \left(\frac{(PLLDIV + 2)}{(PLLPRE + 2) \times 2(PLLPOST + 1)}\right)$$

Where:

$N1 = PLLPRE + 2$

$N2 = 2 \times (PLLPOST + 1)$

$M = PLLDIV + 2$

EQUATION 9-3: FVCO CALCULATION

$$Fvco = FIN \times \left(\frac{M}{N1}\right) = FIN \times \left(\frac{(PLLDIV + 2)}{(PLLPRE + 2)}\right)$$

16.3 PWMx Control Registers

REGISTER 16-1: PTCON: PWMx TIME BASE CONTROL REGISTER

R/W-0	U-0	R/W-0	HS/HC-0	R/W-0	R/W-0	R/W-0	R/W-0
PTEN	—	PTSIDL	SESTAT	SEIEN	EIPU(1)	SYNCPOL(1)	SYNCOEN(1)
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
SYNCEN(1)	SYNCSRC2(1)	SYNCSRC1(1)	SYNCSRC0(1)	SEVTPS3(1)	SEVTPS2(1)	SEVTPS1(1)	SEVTPS0(1)
bit 7							bit 0

Legend:	HC = Hardware Clearable bit	HS = Hardware Settable bit	
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **PTEN:** PWMx Module Enable bit
1 = PWMx module is enabled
0 = PWMx module is disabled

bit 14 **Unimplemented:** Read as ‘0’

bit 13 **PTSIDL:** PWMx Time Base Stop in Idle Mode bit
1 = PWMx time base halts in CPU Idle mode
0 = PWMx time base runs in CPU Idle mode

bit 12 **SESTAT:** Special Event Interrupt Status bit
1 = Special event interrupt is pending
0 = Special event interrupt is not pending

bit 11 **SEIEN:** Special Event Interrupt Enable bit
1 = Special event interrupt is enabled
0 = Special event interrupt is disabled

bit 10 **EIPU:** Enable Immediate Period Updates bit(1)
1 = Active Period register is updated immediately
0 = Active Period register updates occur on PWMx cycle boundaries

bit 9 **SYNCPOL:** Synchronize Input and Output Polarity bit(1)
1 = SYNCI1/SYNCO1 polarity is inverted (active-low)
0 = SYNCI1/SYNCO1 is active-high

bit 8 **SYNCOEN:** Primary Time Base Sync Enable bit(1)
1 = SYNCO1 output is enabled
0 = SYNCO1 output is disabled

bit 7 **SYNCEN:** External Time Base Synchronization Enable bit(1)
1 = External synchronization of primary time base is enabled
0 = External synchronization of primary time base is disabled

Note 1: These bits should be changed only when PTEN = 0. In addition, when using the SYNCI1 feature, the user application must program the period register with a value that is slightly larger than the expected period of the external synchronization input signal.

2: See **Section 24.0 “Peripheral Trigger Generator (PTG) Module”** for information on this selection.

NOTES:

REGISTER 19-3: I2CxMSK: I2Cx SLAVE MODE ADDRESS MASK REGISTER

U-0	U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0
—	—	—	—	—	—	AMSK9	AMSK8
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
AMSK7	AMSK6	AMSK5	AMSK4	AMSK3	AMSK2	AMSK1	AMSK0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-10 **Unimplemented:** Read as ‘0’

bit 9-0 **AMSK<9:0>:** Address Mask Select bits

For 10-Bit Address:

1 = Enables masking for bit Ax of incoming message address; bit match is not required in this position

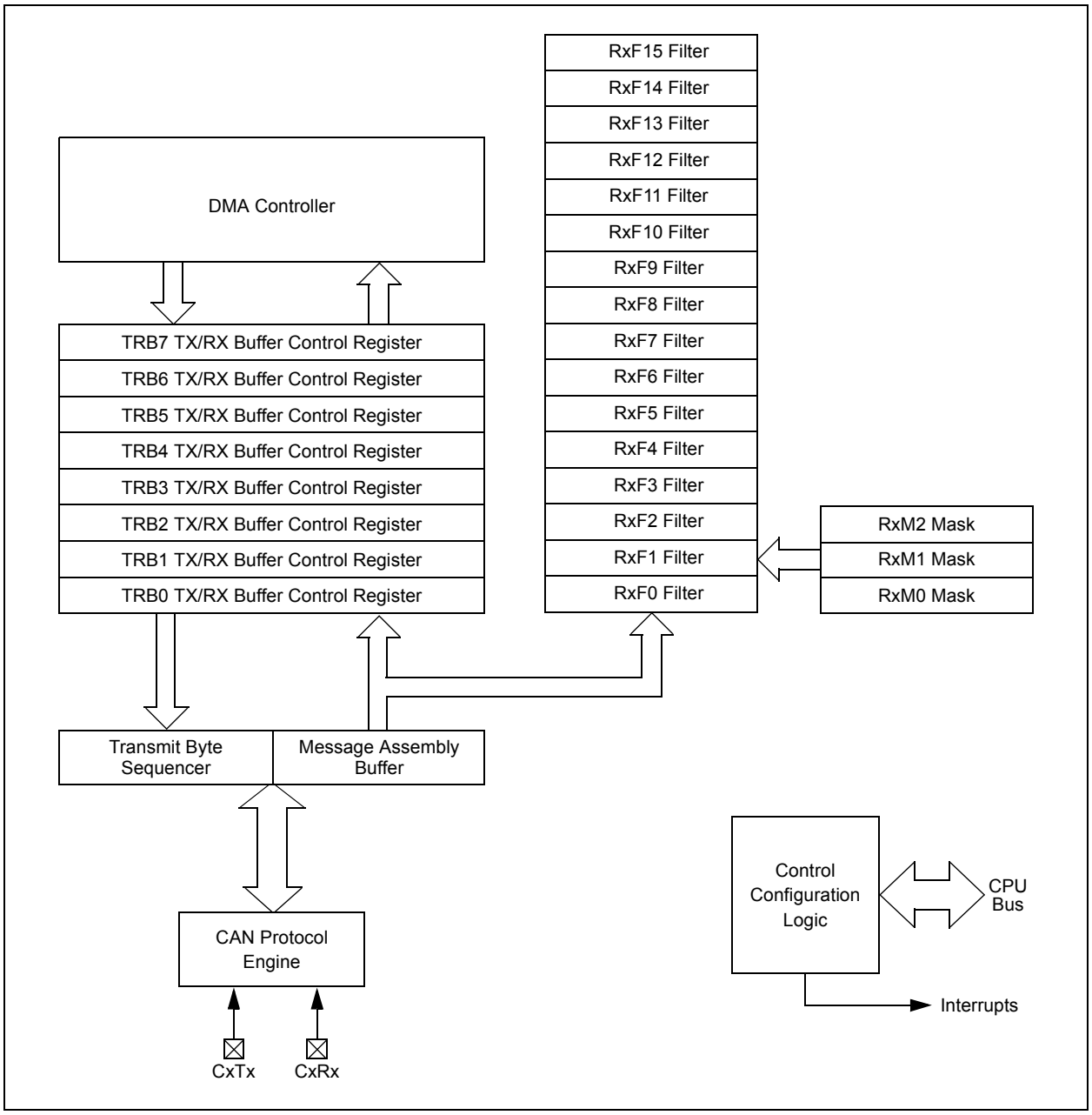
0 = Disables masking for bit Ax; bit match is required in this position

For 7-Bit Address (I2CxMSK<6:0> only):

1 = Enables masking for bit Ax + 1 of incoming message address; bit match is not required in this position

0 = Disables masking for bit Ax + 1; bit match is required in this position

FIGURE 21-1: ECAN™ MODULE BLOCK DIAGRAM



REGISTER 22-3: CTMUICON: CTMU CURRENT CONTROL REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
ITRIM5	ITRIM4	ITRIM3	ITRIM2	ITRIM1	ITRIM0	IRNG1	IRNG0
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-10 **ITRIM<5:0>:** Current Source Trim bits

011111 = Maximum positive change from nominal current + 62%
011110 = Maximum positive change from nominal current + 60%
•
•
•
000010 = Minimum positive change from nominal current + 4%
000001 = Minimum positive change from nominal current + 2%
000000 = Nominal current output specified by IRNG<1:0>
111111 = Minimum negative change from nominal current – 2%
111110 = Minimum negative change from nominal current – 4%
•
•
•
100010 = Maximum negative change from nominal current – 60%
100001 = Maximum negative change from nominal current – 62%

bit 9-8 **IRNG<1:0>:** Current Source Range Select bits

11 = 100 × Base Current(2)
10 = 10 × Base Current(2)
01 = Base Current Level(2)
00 = 1000 × Base Current(1,2)

bit 7-0 **Unimplemented:** Read as ‘0’

Note 1: This current range is not available to be used with the internal temperature measurement diode.

2: Refer to the CTMU Current Source Specifications (Table 30-56) in **Section 30.0 “Electrical Characteristics”** for the current range selection values.

REGISTER 25-5: CMxMSKCON: COMPARATOR x MASK GATING CONTROL REGISTER

R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
HLMS	—	OCEN	OCNEN	OBEN	OBNEN	OAEN	OANEN
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
NAGS	PAGS	ACEN	ACNEN	ABEN	ABNEN	AAEN	AANEN
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **HLMS:** High or Low-Level Masking Select bits
1 = The masking (blanking) function will prevent any asserted ('0') comparator signal from propagating
0 = The masking (blanking) function will prevent any asserted ('1') comparator signal from propagating

bit 14 **Unimplemented:** Read as '0'

bit 13 **OCEN:** OR Gate C Input Enable bit
1 = MCI is connected to OR gate
0 = MCI is not connected to OR gate

bit 12 **OCNEN:** OR Gate C Input Inverted Enable bit
1 = Inverted MCI is connected to OR gate
0 = Inverted MCI is not connected to OR gate

bit 11 **OBEN:** OR Gate B Input Enable bit
1 = MBI is connected to OR gate
0 = MBI is not connected to OR gate

bit 10 **OBNEN:** OR Gate B Input Inverted Enable bit
1 = Inverted MBI is connected to OR gate
0 = Inverted MBI is not connected to OR gate

bit 9 **OAEN:** OR Gate A Input Enable bit
1 = MAI is connected to OR gate
0 = MAI is not connected to OR gate

bit 8 **OANEN:** OR Gate A Input Inverted Enable bit
1 = Inverted MAI is connected to OR gate
0 = Inverted MAI is not connected to OR gate

bit 7 **NAGS:** AND Gate Output Inverted Enable bit
1 = Inverted ANDI is connected to OR gate
0 = Inverted ANDI is not connected to OR gate

bit 6 **PAGS:** AND Gate Output Enable bit
1 = ANDI is connected to OR gate
0 = ANDI is not connected to OR gate

bit 5 **ACEN:** AND Gate C Input Enable bit
1 = MCI is connected to AND gate
0 = MCI is not connected to AND gate

bit 4 **ACNEN:** AND Gate C Input Inverted Enable bit
1 = Inverted MCI is connected to AND gate
0 = Inverted MCI is not connected to AND gate

TABLE 28-2: INSTRUCTION SET OVERVIEW (CONTINUED)

Base Instr #	Assembly Mnemonic	Assembly Syntax		Description	# of Words	# of Cycles(2)	Status Flags Affected
9	BTG	BTG	f,#bit4	Bit Toggle f	1	1	None
		BTG	Ws,#bit4	Bit Toggle Ws	1	1	None
10	BTSC	BTSC	f,#bit4	Bit Test f, Skip if Clear	1	1 (2 or 3)	None
		BTSC	Ws,#bit4	Bit Test Ws, Skip if Clear	1	1 (2 or 3)	None
11	BTSS	BTSS	f,#bit4	Bit Test f, Skip if Set	1	1 (2 or 3)	None
		BTSS	Ws,#bit4	Bit Test Ws, Skip if Set	1	1 (2 or 3)	None
12	BTST	BTST	f,#bit4	Bit Test f	1	1	Z
		BTST.C	Ws,#bit4	Bit Test Ws to C	1	1	C
		BTST.Z	Ws,#bit4	Bit Test Ws to Z	1	1	Z
		BTST.C	Ws,Wb	Bit Test Ws<Wb> to C	1	1	C
		BTST.Z	Ws,Wb	Bit Test Ws<Wb> to Z	1	1	Z
13	BTSTS	BTSTS	f,#bit4	Bit Test then Set f	1	1	Z
		BTSTS.C	Ws,#bit4	Bit Test Ws to C, then Set	1	1	C
		BTSTS.Z	Ws,#bit4	Bit Test Ws to Z, then Set	1	1	Z
14	CALL	CALL	lit23	Call subroutine	2	4	SFA
		CALL	Wn	Call indirect subroutine	1	4	SFA
		CALL.L	Wn	Call indirect subroutine (long address)	1	4	SFA
15	CLR	CLR	f	f = 0x0000	1	1	None
		CLR	WREG	WREG = 0x0000	1	1	None
		CLR	Ws	Ws = 0x0000	1	1	None
		CLR	Acc,Wx,Wxd,Wy,Wyd,AWB(1)	Clear Accumulator	1	1	OA,OB,SA,SB
16	CLRWDT	CLRWDT		Clear Watchdog Timer	1	1	WDTO,Sleep
17	COM	COM	f	$f = \bar{f}$	1	1	N,Z
		COM	f,WREG	$WREG = \bar{f}$	1	1	N,Z
		COM	Ws,Wd	$Wd = \overline{Ws}$	1	1	N,Z
18	CP	CP	f	Compare f with WREG	1	1	C,DC,N,OV,Z
		CP	Wb,#lit8	Compare Wb with lit8	1	1	C,DC,N,OV,Z
		CP	Wb,Ws	Compare Wb with Ws (Wb – Ws)	1	1	C,DC,N,OV,Z
19	CP0	CP0	f	Compare f with 0x0000	1	1	C,DC,N,OV,Z
		CP0	Ws	Compare Ws with 0x0000	1	1	C,DC,N,OV,Z
20	CPB	CPB	f	Compare f with WREG, with Borrow	1	1	C,DC,N,OV,Z
		CPB	Wb,#lit8	Compare Wb with lit8, with Borrow	1	1	C,DC,N,OV,Z
		CPB	Wb,Ws	Compare Wb with Ws, with Borrow ($Wb – Ws – \overline{C}$)	1	1	C,DC,N,OV,Z
21	CPSEQ	CPSEQ	Wb,Wn	Compare Wb with Wn, skip if =	1	1 (2 or 3)	None
	CPBEQ	CPBEQ	Wb,Wn,Expr	Compare Wb with Wn, branch if =	1	1 (5)	None
22	CPSGT	CPSGT	Wb,Wn	Compare Wb with Wn, skip if >	1	1 (2 or 3)	None
	CPBGT	CPBGT	Wb,Wn,Expr	Compare Wb with Wn, branch if >	1	1 (5)	None
23	CPSLT	CPSLT	Wb,Wn	Compare Wb with Wn, skip if <	1	1 (2 or 3)	None
	CPBLT	CPBLT	Wb,Wn,Expr	Compare Wb with Wn, branch if <	1	1 (5)	None
24	CPSNE	CPSNE	Wb,Wn	Compare Wb with Wn, skip if ≠	1	1 (2 or 3)	None
	CPBNE	CPBNE	Wb,Wn,Expr	Compare Wb with Wn, branch if ≠	1	1 (5)	None

Note 1: These instructions are available in dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices only.

2: Read and Read-Modify-Write (e.g., bit operations and logical operations) on non-CPU SFRs incur an additional instruction cycle.

TABLE 30-8: DC CHARACTERISTICS: POWER-DOWN CURRENT (I_{PD})

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended		
Parameter No.	**Typ.**	**Max.**	**Units**	**Conditions**	
Power-Down Current (I_{PD})(1) – dsPIC33EP32GP50X, dsPIC33EP32MC20X/50X and PIC24EP32GP/MC20X					
DC60d	30	100	μA	-40°C	3.3V
DC60a	35	100	μA	+25°C	
DC60b	150	200	μA	+85°C	
DC60c	250	500	μA	+125°C	
Power-Down Current (I_{PD})(1) – dsPIC33EP64GP50X, dsPIC33EP64MC20X/50X and PIC24EP64GP/MC20X					
DC60d	25	100	μA	-40°C	3.3V
DC60a	30	100	μA	+25°C	
DC60b	150	350	μA	+85°C	
DC60c	350	800	μA	+125°C	
Power-Down Current (I_{PD})(1) – dsPIC33EP128GP50X, dsPIC33EP128MC20X/50X and PIC24EP128GP/MC20X					
DC60d	30	100	μA	-40°C	3.3V
DC60a	35	100	μA	+25°C	
DC60b	150	350	μA	+85°C	
DC60c	550	1000	μA	+125°C	
Power-Down Current (I_{PD})(1) – dsPIC33EP256GP50X, dsPIC33EP256MC20X/50X and PIC24EP256GP/MC20X					
DC60d	35	100	μA	-40°C	3.3V
DC60a	40	100	μA	+25°C	
DC60b	250	450	μA	+85°C	
DC60c	1000	1200	μA	+125°C	
Power-Down Current (I_{PD})(1) – dsPIC33EP512GP50X, dsPIC33EP512MC20X/50X and PIC24EP512GP/MC20X					
DC60d	40	100	μA	-40°C	3.3V
DC60a	45	100	μA	+25°C	
DC60b	350	800	μA	+85°C	
DC60c	1100	1500	μA	+125°C	

Note 1: I_{PD} (Sleep) current is measured as follows:

- CPU core is off, oscillator is configured in EC mode and external clock is active; OSC1 is driven with external square wave from rail-to-rail (EC clock overshoot/undershoot < 250 mV required)
- CLKO is configured as an I/O input pin in the Configuration Word
- All I/O pins are configured as inputs and pulled to V_{SS}
- $\overline{MCLR}$ = V_{DD}, WDT and FSCM are disabled
- All peripheral modules are disabled (PMDx bits are all set)
- The VREGS bit (RCON<8>) = 0 (i.e., core regulator is set to standby while the device is in Sleep mode)
- The VREGSF bit (RCON<11>) = 0 (i.e., Flash regulator is set to standby while the device is in Sleep mode)
- JTAG is disabled

TABLE 30-11: DC CHARACTERISTICS: I/O PIN INPUT SPECIFICATIONS (CONTINUED)

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
DI60a	IICL	**Input Low Injection Current**	0	—	-5(4,7)	mA	All pins except VDD, VSS, AVDD, AVSS, MCLR, VCAP and RB7
DI60b	IICH	**Input High Injection Current**	0	—	+5(5,6,7)	mA	All pins except VDD, VSS, AVDD, AVSS, MCLR, VCAP, RB7 and all 5V tolerant pins(6)
DI60c	∑IICT	**Total Input Injection Current (sum of all I/O and control pins)**	-20(8)	—	+20(8)	mA	Absolute instantaneous sum of all ± input injection currents from all I/O pins (| IICL + | IICH |) ≤ ∑IICT

Note 1: The leakage current on the MCLR pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current can be measured at different input voltages.

2: Negative current is defined as current sourced by the pin.

3: See the **"Pin Diagrams"** section for the 5V tolerant I/O pins.

4: VIL source < (VSS – 0.3). Characterized but not tested.

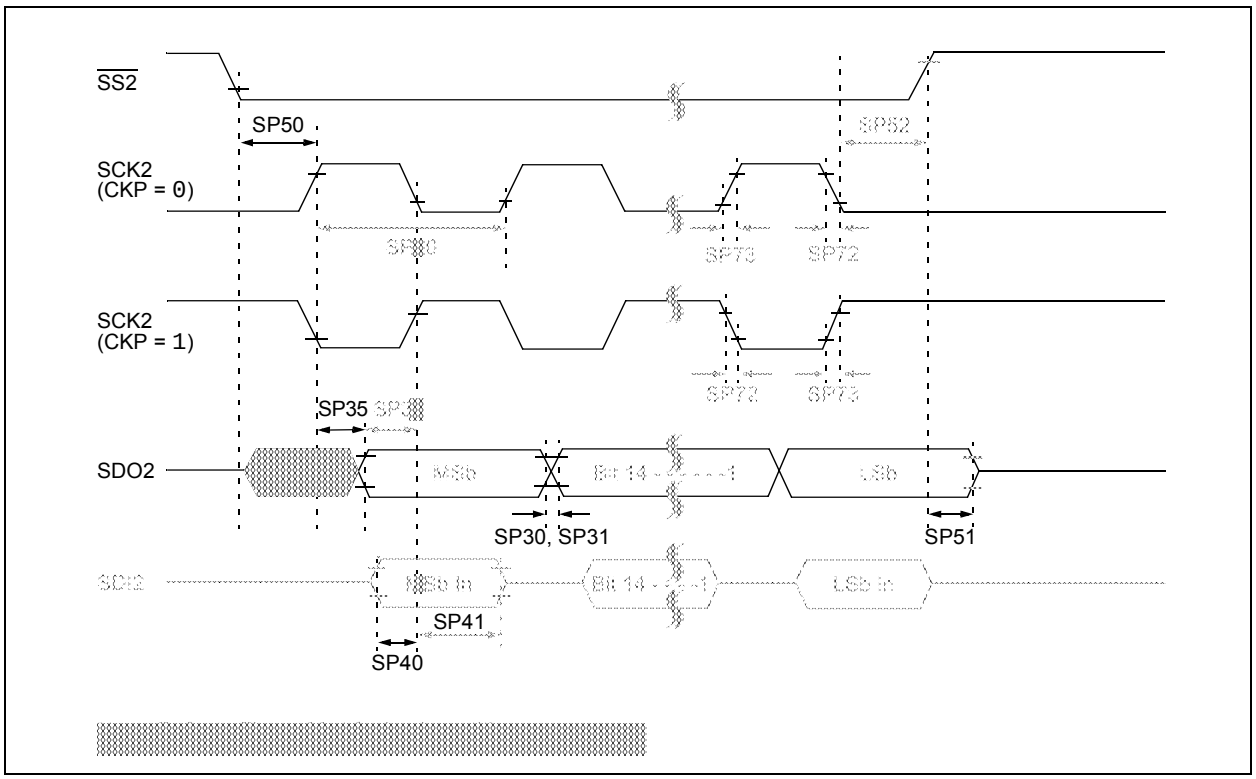
5: Non-5V tolerant pins VIH source > (VDD + 0.3), 5V tolerant pins VIH source > 5.5V. Characterized but not tested.

6: Digital 5V tolerant pins cannot tolerate any "positive" input injection current from input sources > 5.5V.

7: Non-zero injection currents can affect the ADC results by approximately 4-6 counts.

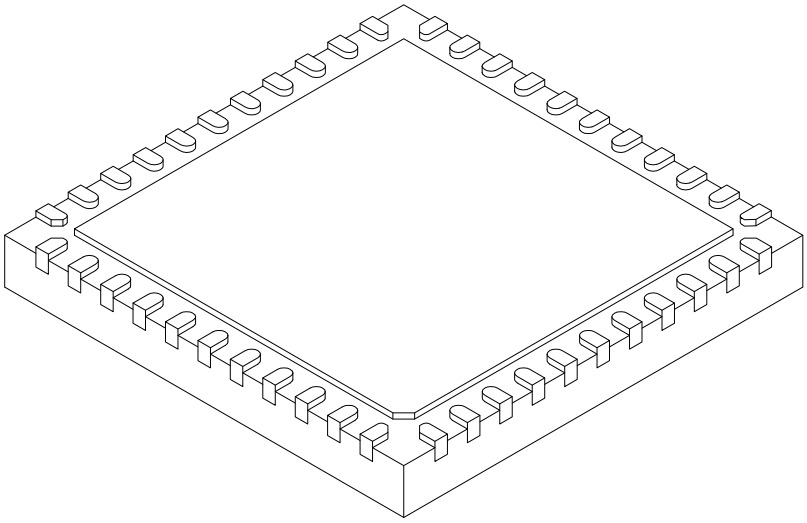
8: Any number and/or combination of I/O pins not excluded under IICL or IICH conditions are permitted provided the mathematical "absolute instantaneous" sum of the input injection currents from all pins do not exceed the specified limit. Characterized but not tested.

FIGURE 30-21: SPI2 SLAVE MODE (FULL-DUPLEX, CKE = 0, CKP = 0, SMP = 0) TIMING CHARACTERISTICS



44-Lead Plastic Quad Flat, No Lead Package (ML) - 8x8 mm Body [QFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		44	
Pitch	e		0.65 BSC	
Overall Height	A	0.80	0.90	1.00
Standoff	A1	0.00	0.02	0.05
Terminal Thickness	A3		0.20 REF	
Overall Width	E		8.00 BSC	
Exposed Pad Width	E2	6.25	6.45	6.60
Overall Length	D		8.00 BSC	
Exposed Pad Length	D2	6.25	6.45	6.60
Terminal Width	b	0.20	0.30	0.35
Terminal Length	L	0.30	0.40	0.50
Terminal-to-Exposed-Pad	K	0.20	-	-

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated
3. Dimensioning and tolerancing per ASME Y14.5M

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

   REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-103C Sheet 2 of 2

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